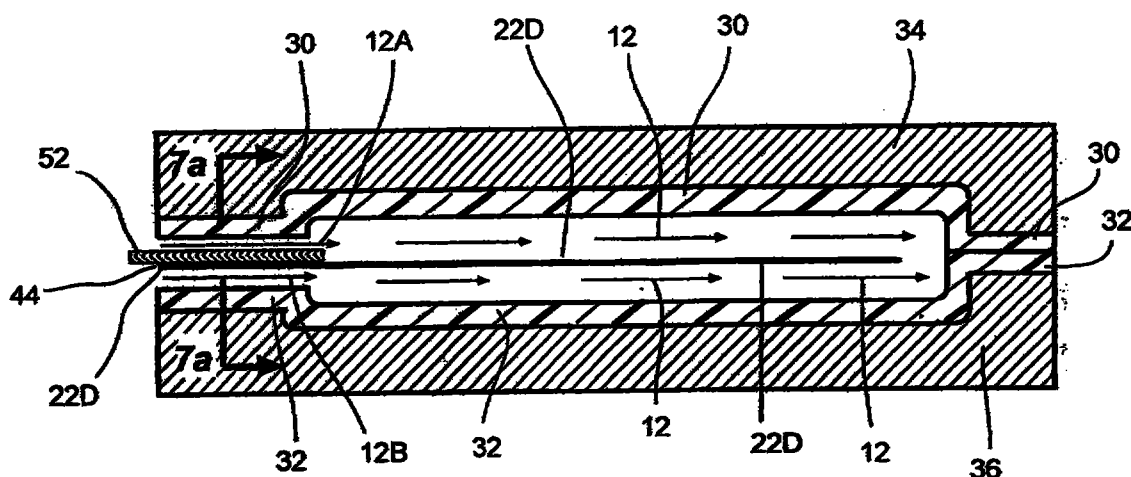




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(21) International Application Number: PCT/US99/05741 (22) International Filing Date: 16 March 1999 (16.03.99) (30) Priority Data: 60/078,262 17 March 1998 (17.03.98) US (71) Applicant: CARDXX, INC. [US/US]; 701 Automation Drive, Windsor, CO 80550 (US). (72) Inventor: TIFFANY, Harry, J., III; 12427 County Road X, Weldona, CO 80653 (US). (74) Agents: CARSON, W., Scott et al.; Dorr, Carson, Sloan & Birney, P.C., 3010 E. 6th Avenue, Denver, CO 80206 (US).		(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>

(54) Title: METHOD FOR MAKING SMART CARDS USING ISOTROPIC THERMOSET ADHESIVE MATERIALS

**(57) Abstract**

Smart cards employing ITA-based circuits (22A-22D) can be made by associating a splitter edge material (52) with the ITA-based circuit (22A-22D) in order to direct an incoming stream (12) of thermosetting polymeric above (12A) and below (12B) the ITA-based circuit (22A-22D).